

ABSTRACT OF THE DISCLOSURE

SUB B2
5 A method of laminating copper foil onto a substrate of a printed circuit board, wherein the substrate has an upper surface and a lower surface. Isolating material is coated onto both surfaces of the substrate to form isolating layers on the substrate. The isolating layers can be formed by roll coating, spray coating or screen printing. The thickness of the isolating layers can be controlled in accordance to the requirements of the circuits. Various types of metal foils can be laminated onto the adhesive layers, followed by heating and pressurization processes to secure the metal foil onto the substrate.

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